To all our customers

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Renesas Technology Home Page: http://www.renesas.com

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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   Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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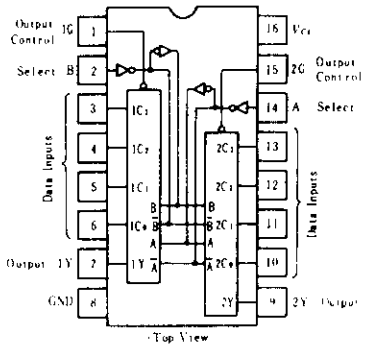
HD74LS253 ●Dual 4-line-to-1-line Data Selectors/Multiplexers (with three-state outputs)

This data selector/multiplexer contains inverters and drivers to supply fully complementary, on-chip, binary decoding data selection to AND-OR gates.

Separate output control inputs are provided for each of the two four-line sections. The three-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at high-impedance state) the low-impedance of the single enabled output will dirve the bus line to a high or low logic level.

■PIN ARRANGEMENT

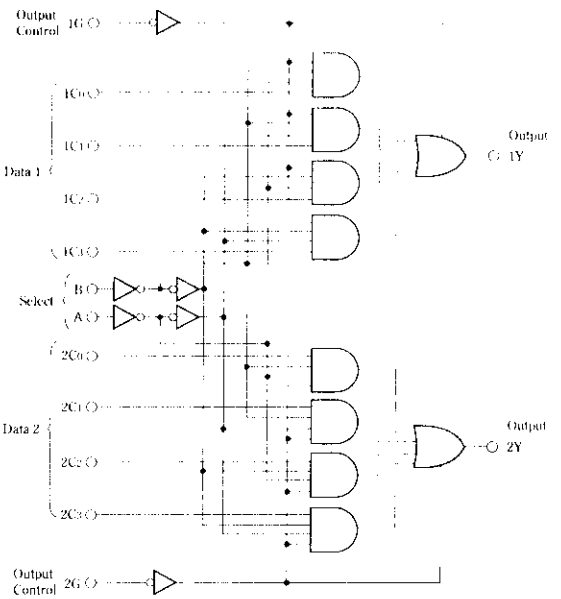


■FUNCTION TABLE

Select inputs		Data inputs				Output control	Output
B	A	C_0	C_1	C_2	C_3	G	Y
×	×	×	×	×	×	H	Z
L	L	L	×	×	×	L	L
L	L	H	×	×	×	L	H
L	H	×	L	×	×	L	L
L	H	×	H	×	×	L	H
H	L	×	×	L	×	L	L
H	L	×	×	H	×	L	H
H	H	×	×	×	L	L	L
H	H	×	×	×	H	L	H

Notes) 1. H; high level, L; low level, X; irrelevant
2. Address inputs A and B are common to both sections.

■BLOCK DIAGRAM



■ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7.0	V
Input voltage	V_{IN}	7.0	V
Output voltage (off-state)	$V_{O(off)}$	5.5	V
Operating temperature range	T_{opr}	−20 ~ +75	℃
Storage temperature range	T_{stg}	−65 ~ +150	℃

■ELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75°C$)

Item	Symbol	Test Conditions		min	typ*	max	Unjt
Input voltage	V_{IH}			2.0	—	—	V
	V_{IL}			—	—	0.8	V
Output voltage	V_{OH}	$V_{CC}=4.75V$, $V_{IH}=2V$, $V_{IL}=0.8V$, $I_{OH}=-2.6mA$		2.4	—	—	V
	V_{OL}	$V_{CC}=4.75V$, $V_{IH}=2V$, $V_{IL}=0.8V$	$I_{OL}=4mA$	—	—	0.4	V
			$I_{OL}=8mA$	—	—	0.5	
Input current	I_{IH}	$V_{CC}=5.25V$, $V_I=2.7V$		—	—	20	μA
	I_{IL}	$V_{CC}=5.25V$, $V_I=0.4V$		—	—	−0.4	mA
	I_I	$V_{CC}=5.25V$, $V_I=7V$		—	—	0.1	mA
Output current	I_{OZ}	$V_{CC}=5.25V$, $V_{IH}=2V$	$V_O=2.7V$	—	—	20	μA
			$V_O=0.4V$	—	—	−20	
Short-circuit output current	I_{OS}	$V_{CC}=5.25V$		−30	—	−130	mA
Supply current**	I_{CC}	$V_{CC}=5.25V$	ConditionA	—	7	12	mA
			ConditionB	—	8.5	14	
Input clamp voltage	V_{IK}	$V_{CC}=4.75V$, $I_{IN}=-18mA$		—	—	−1.5	V

* $V_{CC}=5V$, $Ta=25°C$

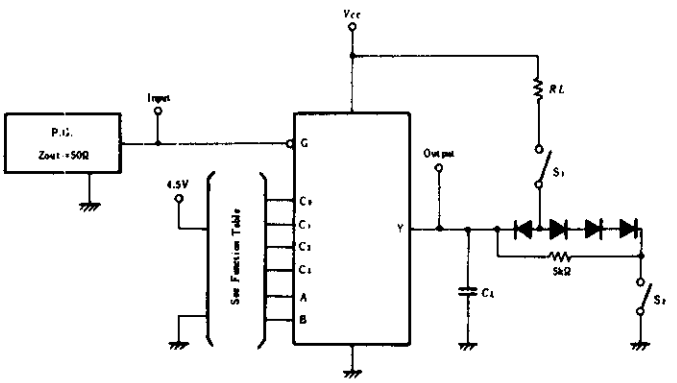
** I_{CC} is measured with the outputs open under the following conditions: A. All inputs grounded, B. Output control at 4.5V, all inputs grounded.

■SWITCHING CHARACTERISTICS ($V_{CC}=5V$, $Ta=25°C$)

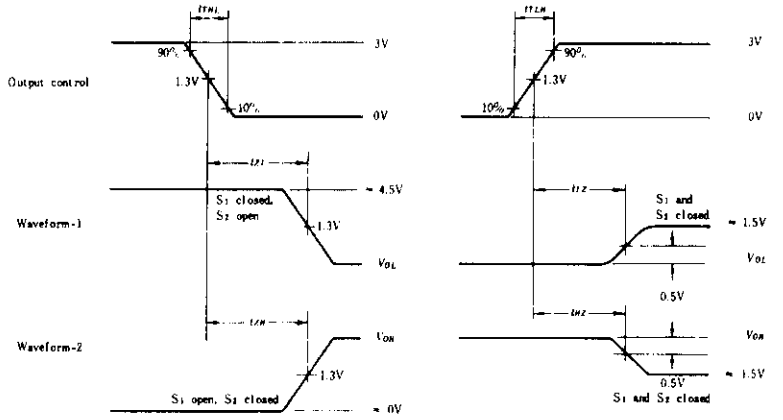
Item	Inputs	Output	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time	Data	Y	t_{PLH}	$C_L=15pF$ $R_L=2k\Omega$	—	17	25	ns
			t_{PHL}		—	13	20	
	Select	Y	t_{PLH}		—	30	45	
			t_{PHL}		—	21	32	
Output enable time	Output Control	Y	t_{ZH}		—	15	28	ns
			t_{ZL}		—	15	23	
Output disable time	Output Control	Y	t_{HZ}	$C_L=5pF$ $R_L=2k\Omega$	—	27	41	ns
			t_{LZ}		—	18	27	

■TESTING METHOD

1) Test Circuit

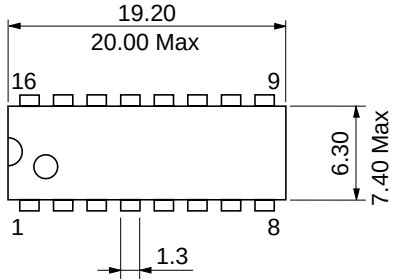


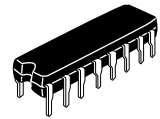
Waveform

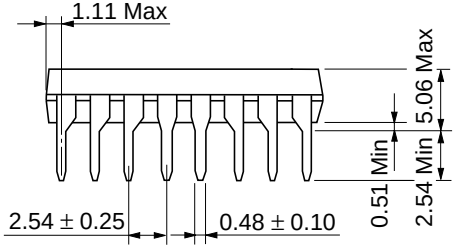


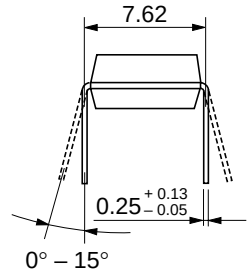
Notes) 1. Input pulse: $t_{TLH} \leqq 15$ns, $t_{THL} \leqq 6$ns, $PRR = 1$MHz, duty cycle = 50%.
2. C_L includes probe and jig capacitance.
3. All diodes are 1S2074 Ⓗ.
4. Waveform-1 is for an output with internal conditions such that the output is low except when disabled by the output control.
5. Waveform-2 is for an output with internal conditions such that the output is high except when disabled by the output control.

Unit: mm



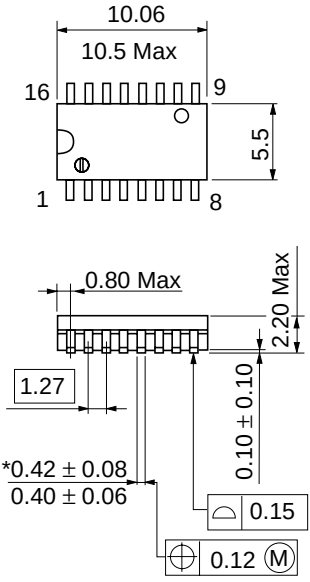


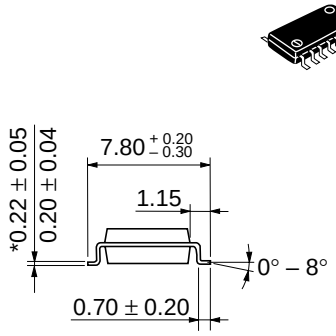


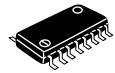


Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.07 g

Unit: mm



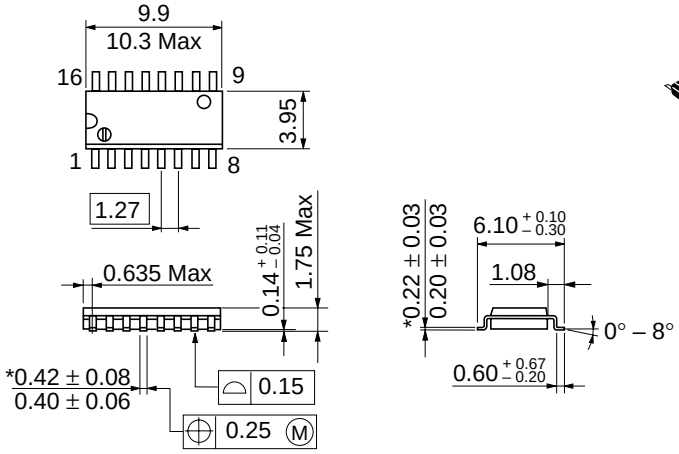




*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.24 g

Unit: mm



Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

*Dimension including the plating thickness
Base material dimension

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